


HC49 - Standard Crystal					Sub-Assembly
Sub-Assembly	Material	Substance	CAS No	Mass (mg)	% by mass
Base Glass	Hard Glass	Al ₂ O ₃	1344-28-1	1.570	10.82
	Hard Glass	K ₂ O	12136-45-7	0.240	1.65
	Hard Glass	K ₂ O	12136-45-7	0.800	5.51
	Tridymite	SiO ₂	14808-60-7	11.900	82.01
Base Header	Chemical Plating	Ni	7440-02-0	3.814	1.03
	Chemical Plating	P	7723-14-0	0.371	0.10
	Electro Plating	Ni	7440-02-0	8.240	2.22
	Steel	C	7440-44-0	0.179	0.05
	Steel	Fe	7439-89-6	358.748	96.44
	Steel	Mn	7439-96-5	0.611	0.16
	Steel	Si	7440-21-3	0.037	0.01
Base clip	Copper Alloy	Cu	7440-50-8	7.014	53.95
	Copper Alloy	Fe	7439-89-6	0.035	0.27
	Copper Alloy	Mn	7439-96-5	0.071	0.55
	Copper Alloy	Ni	7440-02-0	2.149	16.53
	Copper Alloy	Zn	7440-66-6	3.731	28.70
Base terminal wire	Chemical Plating	Ni	7440-02-0	0.434	1.04
	Chemical Plating	P	7723-14-0	0.042	0.10
	High alloyed Steel	C	7440-44-0	0.004	0.01
	High alloyed Steel	Co	7440-48-4	6.868	16.51
	High alloyed Steel	Fe	7439-89-6	21.291	51.18
	High alloyed Steel	Mn	7439-96-5	0.100	0.24
	High alloyed Steel	Ni	7440-02-0	11.687	28.09
	High alloyed Steel	Si	7440-21-3	0.048	0.12
	Solder	Ag	7440-22-4	0.034	0.08
	Solder	Cu	7440-50-8	0.006	0.01
	Solder	Sn	7440-31-5	1.086	2.61
Bonding Adhesive	Silver epoxy	Ag	7440-22-4	2.800	70.00
	Silver epoxy	Epoxy	129915-35-1	1.200	30.00
Cover	Copper Alloy	Cu	7440-50-8	231.300	62.62
	Copper Alloy	Fe	7439-89-6	0.284	0.08
	Copper Alloy	Mn	7439-96-5	0.760	0.21
	Copper Alloy	Ni	7440-02-0	60.876	16.48
	Copper Alloy	Zn	7440-66-6	66.780	18.08
	Electro Plating	Ni	7440-02-0	9.400	2.54
Crystal blank	Quartz	SiO ₂	14808-60-7	27.567	94.84
	Silver plating	Ag	7440-22-4	1.500	5.16

Material Composition Data

Product: HC49

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Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
				Total Mass:	843.577 mg
		 _____	John Hems Quality Manager Email: j.hems@golledge.com		